

IN THE CLAIMS:

1. (Currently Amended) A positive photosensitive composition comprising:

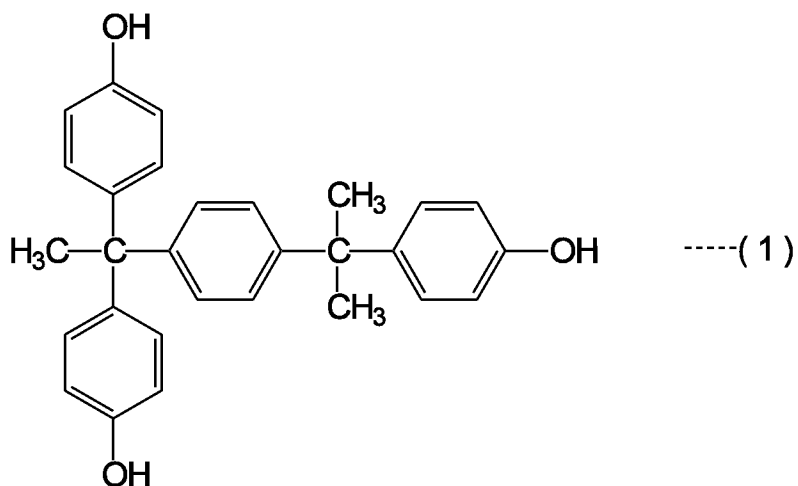
(A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group;[[,]]

(B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat;[[,]]

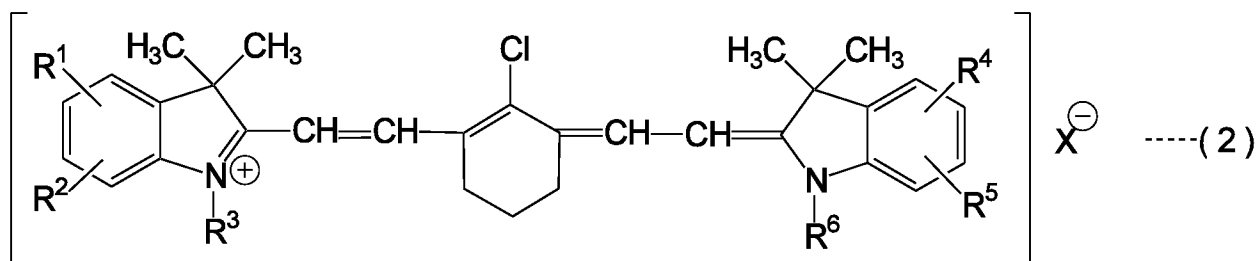
(C) at least one resin selected from the group consisting of: (1) vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethyl- aminoethyl methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal, (7) styrene/maleic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10) melamine/formaldehyde resin, and (11) ketone resin;[[,]] and

(D) a dissolution inhibitor, said alkali soluble organic high molecular substance being in a range from 80 to 95 wt. % of the total solid amount of components (A), (B), (C) and (D), said photo-thermal conversion material being in a range from 0.1 to 10 wt. % of the total solid amount of components (A), (B), (C) and (D), said dissolution inhibitor being in a range from 0.5 to 8 wt. % of the total solid amount of components (A), (B), (C) and (D).

2. (Original) The positive photosensitive composition according to claim 1, wherein the dissolution inhibitor (D) is a compound represented by the following chemical formula (1).



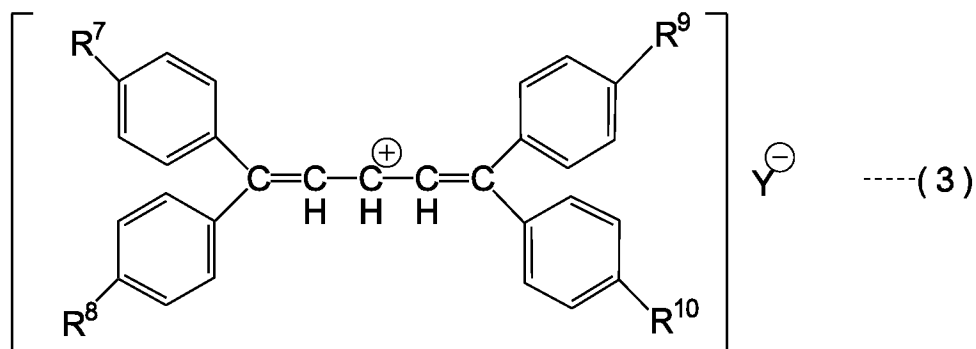
_____3. (Previously Presented) The positive photosensitive composition according to claim 1, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).



wherein each of “R¹” to “R⁶” independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxy group having 1 to 3 carbon atoms, and “X” represents a halogen atom, ClO₄, BF₄, p-CH₃C₆H₄SO₃, or PF₆.

_____4. (Previously Presented) The positive photosensitive composition according to claim 1, wherein the photo-thermal conversion material (B) is a compound represented by the

following formula (3).



wherein each of “R⁷”~“R¹⁰” independently represents a hydrogen atom, a methoxyl group, N(CH₃)₂, or N(C₂H₅)₂, and “Y” represents C₄H₉-B(C₆H₅)₃, p-CH₃C₆H₄SO₃, or CF₃SO₃.

5. (Previously Presented) A photofabrication method comprising:

exposing the positive photosensitive composition as defined in claim 1 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.

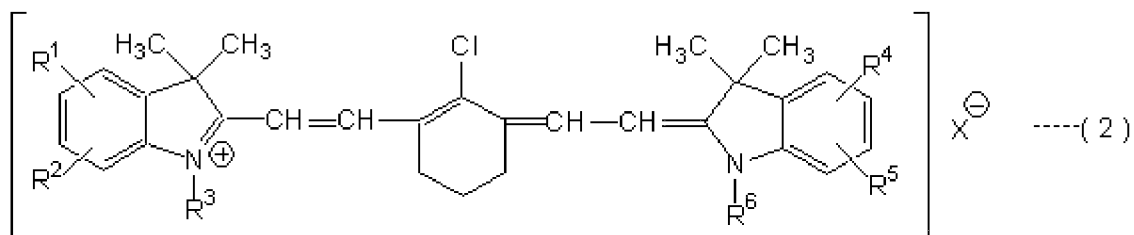
6. (Currently Amended) The photo fabrication method according to claim 5,

[[which]] further comprising the step of applying said photosensitive composition ~~is applied~~ to the production of a printing plate, an electronic component [[and]] or a precision equipment component.

7. (Previously Presented) A plate-making method comprising:

exposing the positive photosensitive composition as defined in claim 1 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.

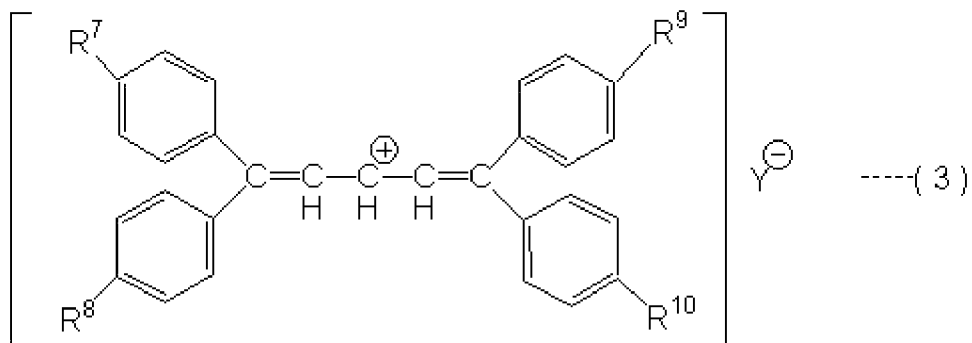
_____8. (Previously Presented) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).



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wherein each of “R¹” to “R⁶” independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxy group having 1 to 3 carbon atoms, and “X” represents a halogen atom, ClO₄, BF₄, p-CH₃C₆H₄SO₃, or PF₆._____

_____9. (Previously Presented) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (3).



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wherein each of “R⁷”~“R¹⁰” independently represents a hydrogen atom, a methoxyl group, N(CH₃)₂, or N(C₂H₅)₂, and “Y” represents C₄H₉-B(C₆H₅)₃, p-CH₃C₆H₄SO₃, or CF₃SO₃.

10. (Previously Presented) A photofabrication method comprising:
exposing the positive photosensitive composition as defined in claim 2 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.

11. (Currently Amended) The photofabrication method according to claim 10,
further comprising the step of applying said positive photosensitive composition ~~which is~~
~~applied~~ to the production of a printing plate, an electronic component ~~[[and]]~~ or a precision equipment component.

12. (Previously Presented) A plate-making method comprising:
exposing the positive photosensitive composition as defined in claim 2 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.